

MicroStar BGA Discontinued and Redesigned



High Speed Signal Conditioning

ABSTRACT

This document should be used in conjunction with the device data sheet and describes the updated package designator for the indicated devices.

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Trademarks

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1 Package Redesign Details

Explanation

The devices in the MicroStar BGA™ packaging were redesigned using a laminate nFBGA package. The nFBGA package offers data sheet-equivalent electrical performance and data sheet-equivalent or better thermal performance. It provides the same X and Y dimensions as MicroStar BGA, and provides pin-to-pin and footprint compatibility. The nFBGA PCB land pattern and stencil recommendations have been updated to achieve better soldering results after extensive testing and evaluation. For more details, please refer to this [nFBGA Package Application Report](#).

When referencing the device data sheet, use the new package designator in place of the discontinued package designator throughout the document.

The orderable addendum at the end of the device data sheet will reflect the new package designator.

See the following page or the end of the device data sheet for the updated nFBGA package drawing.

Table 1-1. Package Designator

Old Package Designator	New Package Designator
ZGU	ZWS
ZHK	ZWT
ZGB	ZWS
ZHH	ZAY
ZZZ	ZAV
ZHC	NMH

Reason for Discontinuance

Due to an equipment End-Of-Life notice from our substrate supplier, we are phasing out certain MicroStar BGA and MicroStar Junior™ BGA packaging devices and offering a Last Time Buy.

These devices have now been converted to an nFBGA package.

Devices Affected

The following table describes the devices affected, the old and new package designators, and references to the device data sheet.

Table 1-2. Devices and Nomenclature

Device	Discontinued MicroStar BGA Device	Redesigned Laminate nFBGA Device	Device Data Sheet
PCI1510	PCI1510 ZGU	PCI1510 ZWS	SCPS071E
PCI1520	PCI1520 ZHK	PCI1520 ZWT	SCPS065D
PCI1520	PCI1520 ZHK	PCI1520 ZWT	SCPS065D
PCI2050	PCI2050 BZHK	PCI2050 BZWT	SCPS076G
PCI2050	PCI2050 BZHK	PCI2050 BZWT	SCPS076G
XIO1100	XIO1100 ZGB	XIO1100 ZWS	SLLS690C
XIO1100	XIO1100 ZGBR	XIO1100 ZWSR	SLLS690C
XIO2000	XIO2000 AZHH	XIO2000 AZAY	SCPS155C
XIO2000	XIO2000 AZZZ	XIO2000 AZAV	SCPS155C
XIO3130	XIO3130 ZHC	XIO3130 NMH	SLLS693F
XIO3130	XIO3130 ZHC	XIO3130 NMH	SLLS693F

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